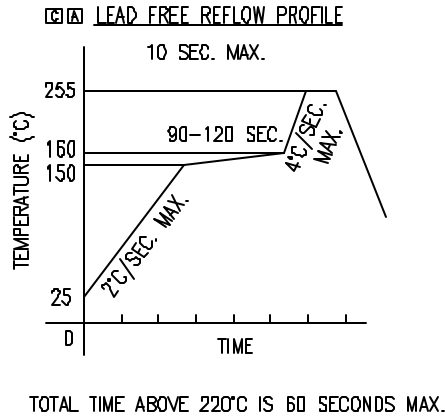
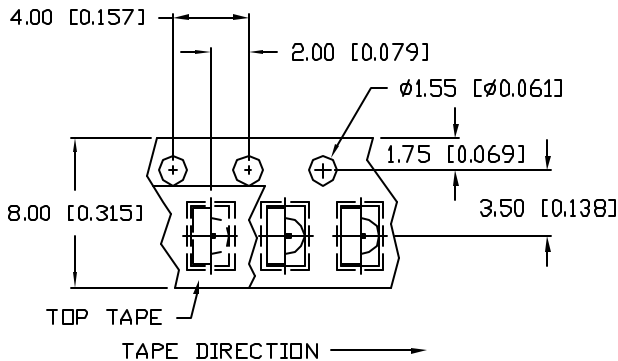
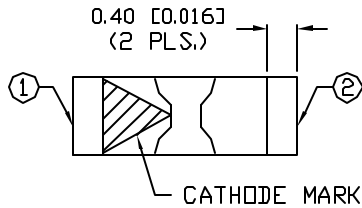
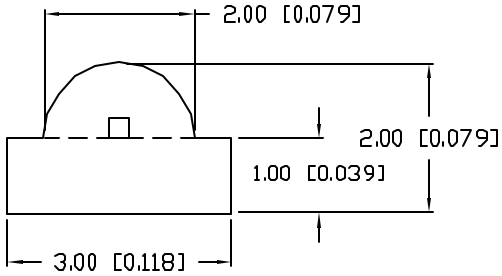
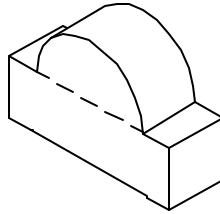
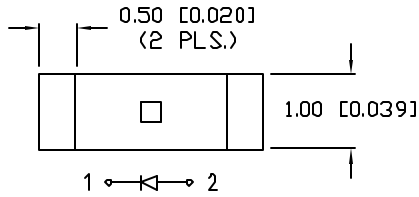
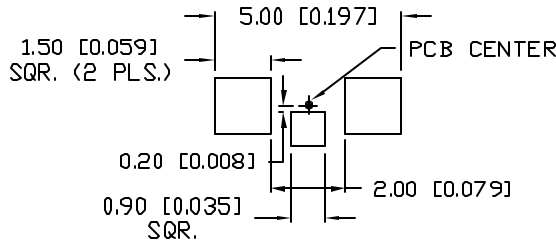


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TOTAL TIME ABOVE 220°C IS 60 SECONDS MAX.

RECOMMENDED PAD LAYOUT



PART NUMBER  
SML-LXR851YC-TR

REV.  
C

REV.	E.C.N. NUMBER AND REVISION COMMENTS	DATE
A	E.C.N. #10644	7.18.00
B	E.C.N. #10967.	9.07.04
C	E.C.N. #11148.	04.21.08

ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		585		nm	
FORWARD VOLTAGE		2.1	2.5	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_f=100\mu\text{A}$
AXIAL INTENSITY		6		mcd	$I_f=20\text{mA}$
VIEWING ANGLE		160		2x theta	
EMITTED COLOR:	YELLOW				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	160	mA
STEADY CURRENT	30	mA
POWER DISSIPATION	100	mW
DERATE FROM 25°C	-1.2	mW/°C
OPERATING TEMP.	-25 TO +85	°C
STORAGE TEMP.	-30 TO +85	°C

\*  $t < 10\mu\text{s}$

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

NOTES:

- 2,000 PER REEL.
- THE CATHODE IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.



UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), XX=±0.5 (±0.020), XXX=±0.25 (±0.010), XXXX=±0.127 (±0.005). LEAD SIZE=±0.05 (0.002), LEAD LENGTH=±0.75 (±0.030), MIN= +DECIMAL PRECISION -0.00, MAX.= +0.00 -DECIMAL PRECISION

REV. C PART NUMBER SML-LXR851YC-TR

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1.0mm x 3.0mm PCB RIGHT ANGLE SURFACE MOUNT LED,  
585nm YELLOW, WATER CLEAR LENS, 2K PER REEL.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: BC CHECKED BY: APPROVED BY: DATE: 10.22.98  
PAGE: 1 OF 1  
SCALE: N/A